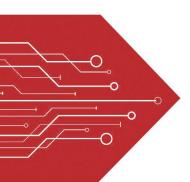
## MSKSEMI















**ESD** 

TVS

TSS

MOV

GDT

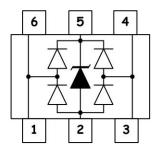
**PLED** 

# Broduct data sheet



SOT-23-6

## **Pin Configuration**



#### **Features**

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity testAir discharge: ±30kV

Contact discharge: ±25kV

- IEC61000-4-4 (EFT) 4.5A (5/50ns)
- RoHS Compliant

## **Applications**

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)

## **Mechanical Characteristics**

Package: SOT-23-6

• Lead Finish: Lead Free

• UL Flammability Classification Rating 94V-0

• Quantity Per Reel:3,000pcs

Reel Size:7inch

## **Absolute Maximum Ratings**(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	Ррр	150	W
ESD per IEC 61000-4-2 (Air)	\/	±20	Kv
ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	±15	KV
Operating Temperature Range	TJ	-55 to +125	$^{\circ}$ C
Storage Temperature Range	T <sub>STJ</sub>	-55 to +150	${\mathbb C}$



## **Electrical Characteristics**(TA=25°C unless otherwise specified)

P/N	Marking	V <sub>RWM</sub> (V)	V <sub>BR</sub> (V)	I⊤ (mA)	V <sub>c</sub> @1A	(Max)	(@A)	I <sub>R</sub> μΑ (Max)	C (Pf) (Typ.)
USBLC6-2SC6-MS	UL26	5	6	1	9.8	15	4.5	1	0.3

## **Characteristic Curves**

Fig1.  $8/20\mu$  s Pulse Waveform

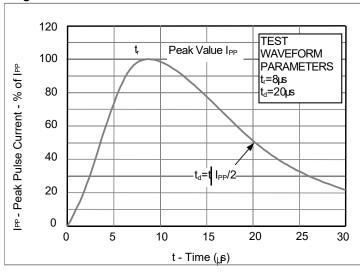


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

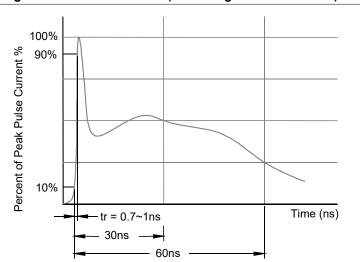
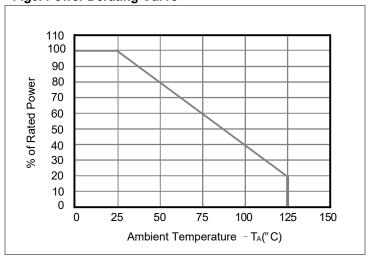
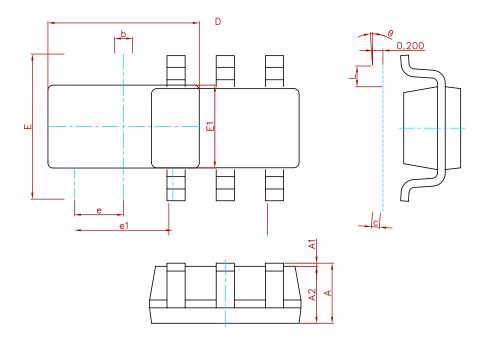


Fig3. Power Derating Curve

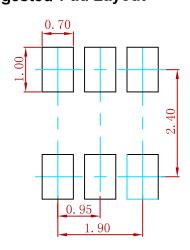


## PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
Syllibol	Min.	Max.	Min.	Max.
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
Е	2.650	2.950	0.104	0.116
е	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

## **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters. 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
USBLC6-2SC6-MS	SOT-23-6	3000



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